Lecture 14 The pn Junction Diode (I) I-V Characteristics

Outline

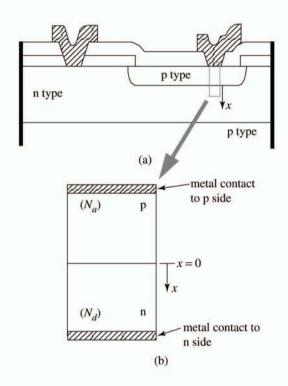
- pn junction under bias
- IV characteristics

Reading Assignment:

Howe and Sodini; Chapter 6, Sections 6.1-6.3

1. PN junction under bias

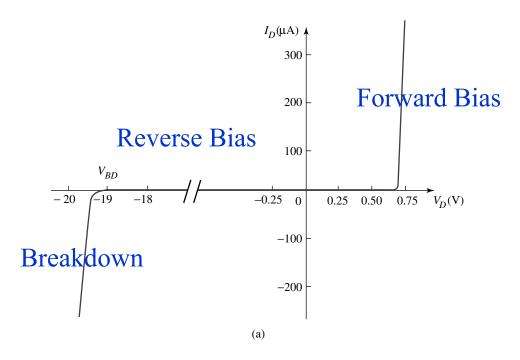
Focus on intrinsic region:

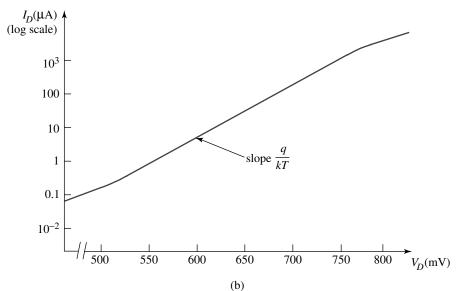


Upon application of voltage:

- Electrostatics upset:
 - depletion region widens or shrinks
- · Current flows
 - With rectifying behavior
- Carrier charge storage

I-V Characteristics

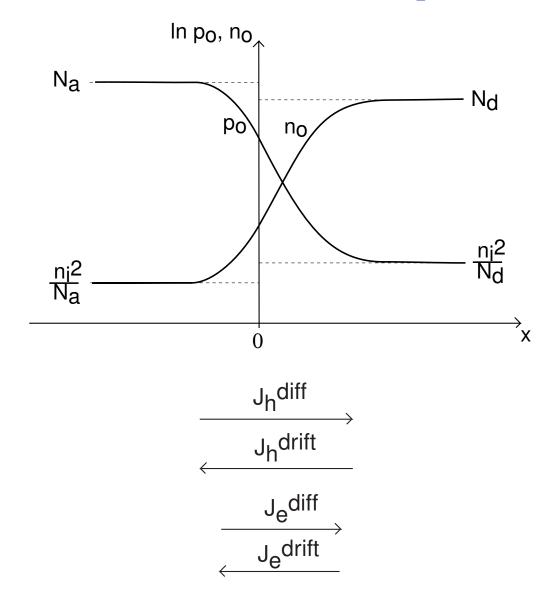




To model I-V characteristics we need 2 concepts

- The Law of the Junction
- Steady-State Diffusion

Carrier Profiles: in thermal equilibrium

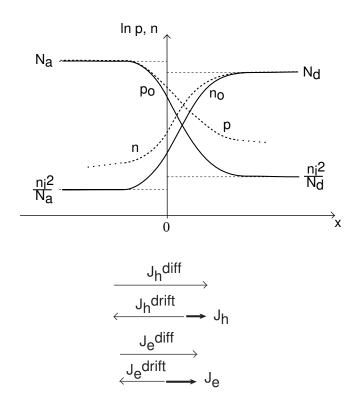


In equilibrium: dynamic balance between drift and diffusion for electrons and holes inside SCR.

$$\left| J_{drift} \right| = \left| J_{diff} \right|$$

Carrier Profiles: under forward bias

For V>0,
$$\phi_B$$
 - V $\downarrow \Rightarrow |E_{SCR}| \downarrow \Rightarrow |J_{drift}| \downarrow$



Current balance in SCR broken:

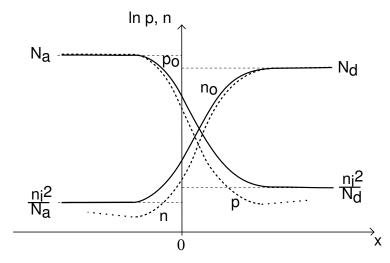
$$\left| J_{drift} \right| < \left| J_{diff} \right|$$

Net diffusion current in SCR \Rightarrow minority carrier *injection* into QNRs.

Carrier flow can be high because lots of minority carriers are injected into QNRs from the majority side.

Carrier Profiles: under reverse bias

For V<0, ϕ_B - V $\uparrow \Rightarrow |E_{SCR}| \uparrow \Rightarrow |J_{drift}| \uparrow$



$$J_{h} \leftarrow J_{h}^{diff}$$

$$\downarrow J_{e}^{diff}$$

$$\downarrow J_{e}^{diff}$$

Current balance in SCR broken:

$$\left|J_{drift}\right| > \left|J_{diff}\right|$$

Net drift current in SCR \Rightarrow minority carrier *extraction* from QNRs.

Carrier flow is small because there are few minority carriers extracted from QNRs from the minority side.

Minority Carrier Concentrations: in QNR

What happens if minority carrier concentrations in QNR changed from equilibrium?

- ⇒ Balance between generation and recombination is broken
- In thermal equilibrium: rate of break-up of Si-Si bonds balanced by rate of formation of bonds

Si-Si bond
$$n_0 + p_0$$
 recombination

• If minority carrier injection: carrier concentration above equilibrium and recombination prevails

• If minority carrier extraction: carrier concentrations below equilibrium and generation prevails

Where does generation and recombination take place?

- 1. Semiconductor bulk
- 2. Semiconductor surfaces & contacts

In modern silicon pn-junction devices, surface & contact recombination dominates because:

- Prefect crystalline periodicity broken at the surface
 - \Rightarrow lots of generation and recombination centers;
- Modern devices are small
 - \Rightarrow high surface area to volume ratio.

Surfaces and contacts are very active generation and recombination centers

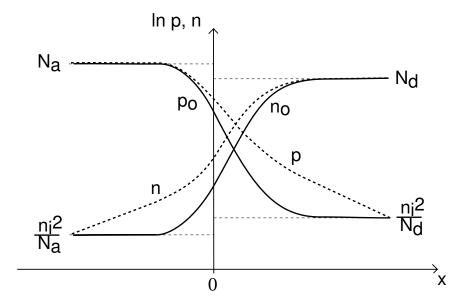
⇒ *at contacts*, carrier concentrations cannot deviate from equilibrium:

In general, it is assumed that at contacts, the rate at which generation/recombination takes place is *infinite*.

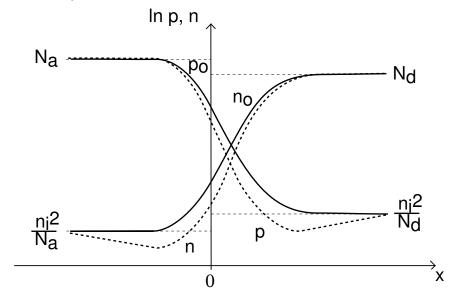
$$n_c = n_o$$
; $p_c = p_o$

Complete physical picture for pn diode under bias:

• In forward bias, injected minority carriers diffuse through QNR and recombine at semiconductor surface.



• In reverse bias, minority carriers generated at the semiconductor surface, diffuse through the QNR, and extracted by SCR.



What is the barrier (Bottleneck) to current flow?

- Not generation or recombination at surfaces,
- Not injection or extraction through SCR
- But minority carrier *diffusion* through the QNRs

Development of analytical current model:

- 1. Calculate the concentration of minority carriers at edges of SCR;
- 2. Find the spatial distribution of the minority carrier concentrations in each QNR;
- 3. Calculate minority carrier diffusion current at SCR edge.
- 4. Sum minority carrier electron and hole diffusion currents at SCR edge.

2. I-V Characteristics

STEP 1: Computation of minority carrier boundary conditions at the edges of the SCR

In thermal equilibrium in SCR, $|J_{drift}| = |J_{diff}|$

- Define $p_{no} = n_i^2/N_d$ and $n_{po} = n_i^2/N_a$
- Recall

$$\phi_B = \frac{kT}{q} \ln \left(\frac{N_a N_d}{n_i^2} \right)$$

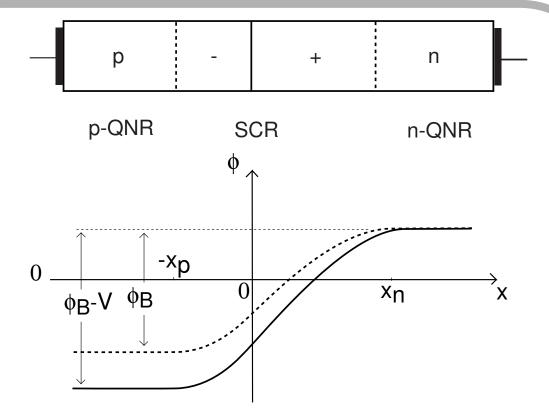
• Rewrite

$$\phi_B = V_{th} \ln \left(\frac{N_d}{n_{po}} \right)$$
 and $\phi_B = V_{th} \ln \left(\frac{N_a}{p_{no}} \right)$

• Solving for the equilibrium minority carrier concentrations in terms of the built-in potential,

$$p_{no} = N_a e^{-\frac{\phi_B}{V_{th}}}$$
 and $n_{po} = N_d e^{-\frac{\phi_B}{V_{th}}}$

This result relates the minority carrier concentration on one side of the junction to the majority carrier concentration on the *other side* of the junction



- The new potential barrier $\phi_j = (\phi_B V_D)$ is substituted for the thermal equilibrium barrier to find the new minority carrier concentrations at the SCR edges.
- Assume the detailed balance between drift and diffusion is not significantly perturbed. This says electrons are in equilibrium with each other across the junction. SAME for holes.

$$n_{p}(-x_{p}) = N_{d}e^{\frac{-\phi_{j}}{V_{th}}} = N_{d}e^{\frac{-(\phi_{B}-V_{D})}{V_{th}}}$$

and

$$p_{n}(x_{n}) = N_{a}e^{\frac{-\phi_{j}}{V_{th}}} = N_{a}e^{\frac{-(\phi_{B}-V_{D})}{V_{th}}}$$

Law of the Junction

$$n_{p}(-x_{p}) = N_{d}e^{\left[\frac{-\phi_{B}}{V_{th}}\right]_{e}\left[\frac{V_{D}}{V_{th}}\right]_{e}} = n_{po}e^{\left[\frac{V_{D}}{V_{th}}\right]_{e}}$$

and

$$p_{n}(x_{n}) = N_{a}e^{\left[\frac{-\phi_{R}}{V_{th}}\right]}e^{\left[\frac{V_{D}}{V_{th}}\right]} = p_{no}e^{\left[\frac{V_{D}}{V_{th}}\right]}$$

where
$$n_{po} = \frac{n_i^2}{N_a}$$
 and $p_{no} = \frac{n_i^2}{N_d}$

- The minority carrier concentration at the SCR is an exponential function of applied bias. It changes one decade for every 60mV change in V_D
- Law of the Junction is valid if minority carrier concentration is less than equilibrium majority concentration. This condition is called Low Level Injection.

$$p_n < n_{no}$$
 and $n_p < p_{po}$

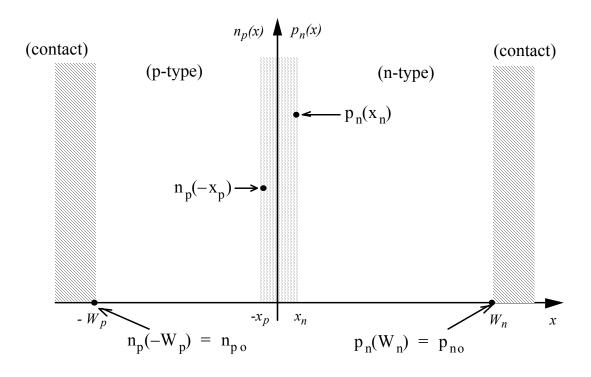
Voltage Dependence:

• Forward bias (V>0):

$$n_p(-x_p) >> n_{po}(-x_{po})$$

$$p_n(x_n) >> p_{no}(x_{no})$$

- Lots of carriers available for injection, the higher V, the higher the concentration of injected carriers ⇒ forward current can be high.
- Minority carrier concentration is maintained at thermal equilibrium at the ohmic contacts. All excess carriers recombine at ohmic contact.



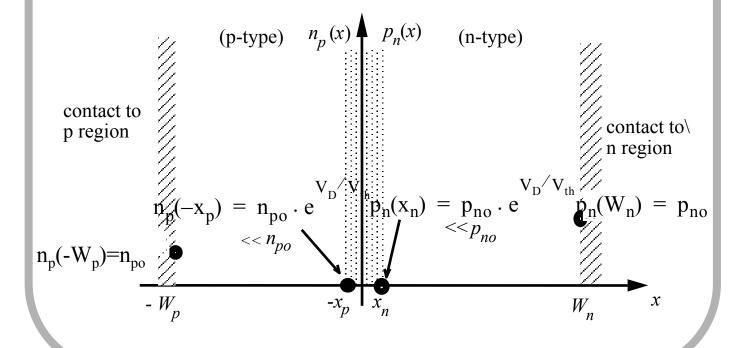
• Reverse bias (V<0):

$$n_p(-x_p) << n_{po}(-x_{po})$$
 $p_n(x_n) << p_{no}(x_{no})$

Few carriers available for extraction ⇒ reverse current is small.

There is limit in reverse bias to how low minority carrier concentrations at SCR edge can be: zero!

Rectification property of the pn diode arises from minority-carrier boundary conditions at edges of SCR.



What did we learn today?

Summary of Key Concepts

- Application of voltage to pn junction results in disruption of balance between drift and diffusion in SCR
 - In forward bias, minority carriers are *injected* into quasi-neutral regions
 - In reverse bias, minority carriers are *extracted* from the quasi-neutral regions
- In forward bias, injected minority carriers recombine at the surface (contacts).
- In reverse bias, extracted minority carriers are generated at the surface (contacts).
- Computation of boundary conditions across SCR exploits *quasi-equilibrium*: balance between diffusion and drift in SCR disturbed very little
- IV characteristics of p-n diode: Next Time

$$I = I_o \left(e^{\left[\frac{V}{V_{th}} \right]} - 1 \right)$$

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6.012 Microelectronic Devices and Circuits Spring 2009

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